

Examiner: *gy*

AN 1998:767861 HCAPLUS
DN 130:55715
TI Lead-free **tin** alloy solders for printed circuit board showing
excellent melting property, wettability and mechanical strength
IN Takeda, Naoko; Hanyu, Kazutaka
PA Sony Corp., Japan
SO Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 10314980	A2	19981202	JP 1997-124445	19970514
AB	The alloys are Sn alloys contg. Bi 1.0-12.0, Ag 0.5-6.0, Cu 0.1-3.0, and In 0.5-10 wt.%. 				